

Lead-Free Solder Bar

Model: PF665-B

Rev.2012/10/08 Ver.03-00

— Specification —

Item	Specification
Alloy Composition	Sn/Cu0.7/Ni0.025/Ge0.01/Ag0.05
Appearance	Bright and shiny surface finishes.
Shape	Bar.
Density	Approx. 7.3 g/cm ³ (20°C) °
Melting Point	Approx. 227~228°C.
Packaging	Net weight Approx. 20kg/carton.
Feature	Produced by pure tin, silver and copper. Impurities are lowed to the minimum.
Application	For wave soldering process.
Reference Standard	JIS-Z-3282
Storage and Handling	Storage must be in a dry, non-corrosive and shine environment.
Shelf life	Shelf life is 2 years from date of manufacture.

— Alloy Composition —

Sn	Cu	Ag	Ni	Ge	Pb	Sb	Bi	Cd	Au	In	Al	As	Fe	Zn
REM.	0.5~ 0.9	0.03~ 0.07	0.02~ 0.03	0.005~ 0.02	0.05 Max	0.05 Max	0.10 Max	0.002 Max	0.05 Max	0.10 Max	0.001 Max	0.03 Max	0.02 Max	0.001 Max

Patent No.: U.S Patent No. 6179935B1. Germany Patent No.19816671C2.

(wt %)

All alloy of SHENMAO' products were to conform to SONY Green Partner and comply RoHS requirement.

Contact Information

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BRANCHES:

Please refer to our website.

 Website: <http://www.shenmao.com>